

**REMARKS**

Claims 1, 3, 5, 7-10 and 22 have been amended, and new claims 28-38 have been added.


Claims 1, 3, 5, 7 and 9 have been amended to clarify the difference between the present invention and JP 2000-277794 (submitted with the Information Disclosure Statement filed on December 27, 2005). Specifically, claims 1 and 3 have been amended to add "with an interlayer insulating film interposed therebetween" after "wherein the first semiconductor element and the second semiconductor element are stacked." The feature is supported in the present specification, for example, by Figure 3 (e.g. reference number 523). With respect to claims 5 and 7, the feature "an interlayer insulating film formed between the first semiconductor element and the resin film" has been added. Also, in claims 9 and 10, the Applicant has changed "a first thin film integrated circuit including at least one thin film transistor and a light emitting element and an interface" to "a first thin film integrated circuit including at least one thin film transistor, [[and]] a light emitting element, an interlayer insulating film, and an interface."

Claims 8 and 22 have been amended to correct minor informalities.

Also, new claims 28-38 have been added including independent claims 28-30. These features are supported in the present specification, for example, by Figure 14 and Embodiment 7.

Examination on the merits is respectfully requested.

Respectfully submitted,



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